

ABSTRACT OF THE DISCLOSURE

A method of bonding a common cover plate over a plurality of OLED devices formed on a device substrate includes providing an unpatterned or
5 a patterned layer of a pressure-sensitive adhesive (PSA) material over a surface of the cover plate; bonding the cover plate over the OLED devices; and singulating individual OLED devices having a bonded cover plate and permitting electrical access to electrical interconnects associated with each OLED device for attaching electrical leads thereto.